

F

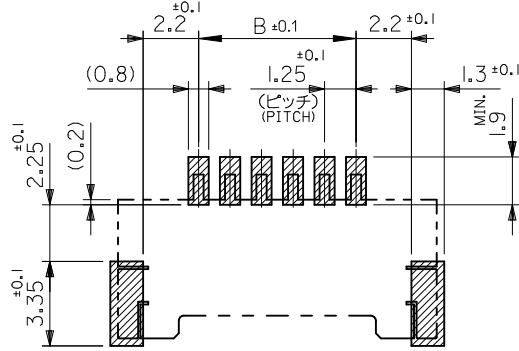
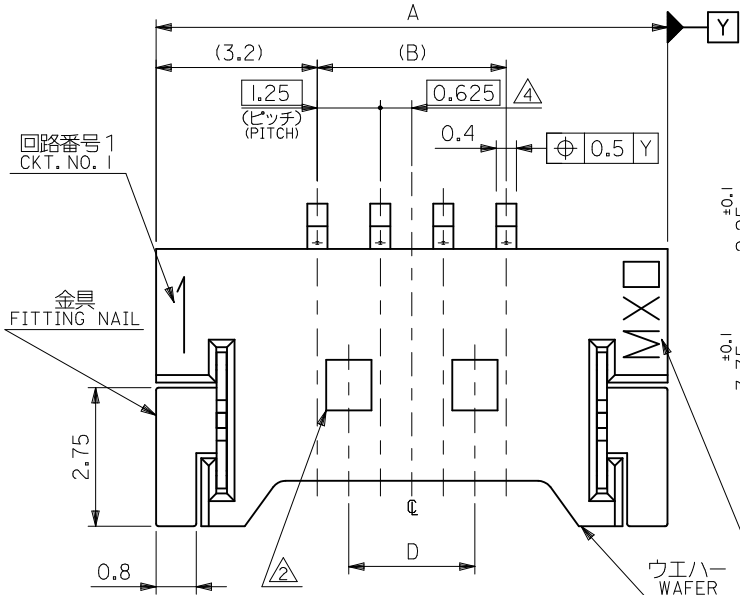
E

D

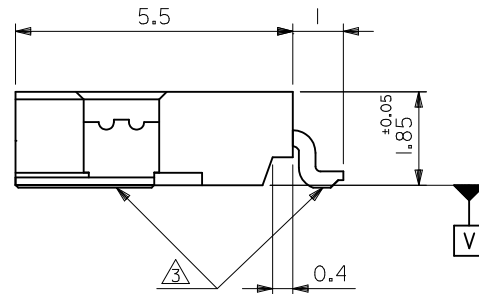
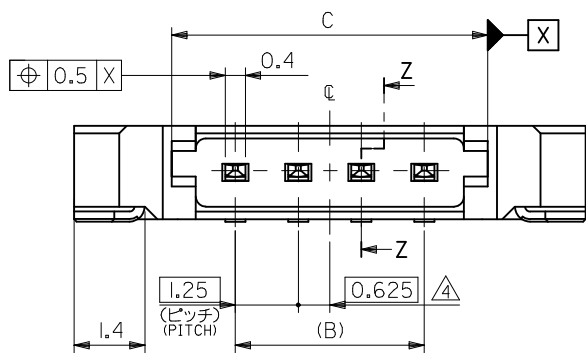
C

B

A



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM. (REF.)




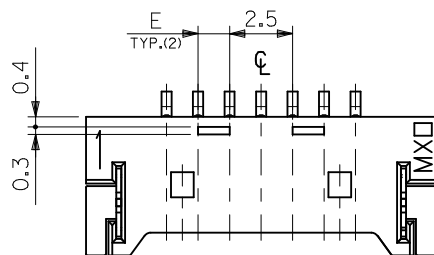
注記 NOTES

- 嵌合相手: 51146 シリーズ
MATES WITH: 51146 SERIES
- ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS
AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
- 基準面 [V] からのソルダテールと金具の半田付け面のズレ量は、
上方向に 0.05MAX.、下方向 0.15MAX.、とし、20 極以下の相互の
バラツキ量は 0.1MAX. とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V]
: UPPER DIRECTION 0.05MAX.
: LOWER DIRECTION 0.15MAX.
: OFFSET BETWEEN UPPER AND LOWER 0.1MAX. (UNDER 20 CKTS.)
- 偶数極の製品に適用。
APPLY EVEN CIRCUIT PRODUCTS.
- 材質 MATERIAL
ウエハー: WAFER: PPS, UL94V-0
ピン: リン青銅 PIN: PHOSPHOR BRONZE
コンタクト部: 金メッキ 0.2 マイクロメートル以上
CONTACT AREA: GOLD 0.2 MICROMETER MINIMUM
テール部: 銅メッキ 3.0 マイクロメートル以上
TAIL AREA: TIN 3.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
金具: リン青銅 FITTING NAIL: PHOSPHOR BRONZE
銅メッキ 3.0 マイクロメートル以上
TIN 3.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0 マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
- 本製品は 53780-**-**10/-**-**18 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53780-**-**10/-**-**18.
- ELV 及び RoHS 適合品
ELV & RoHS COMPLIANT.

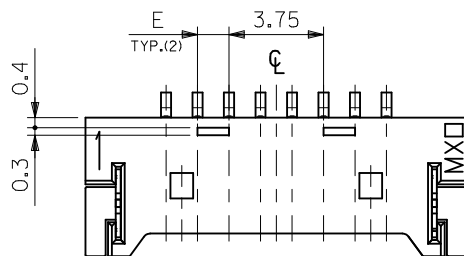
16.25	22.5	38.77	36.25	42.65	53780-3070	30
8.75	22.5	26.27	23.75	30.15	-2070	20
7.5	20	23.77	21.25	27.65	-1870	18
6.25	16.25	20.02	17.5	23.9	-1570	15
5	15	18.77	16.25	22.65	-1470	14
3.75	12.5	16.27	13.75	20.15	-1270	12
2.5	10	13.77	11.25	17.65	-1070	10
2.5	8.75	12.52	10	16.4	-0970	9
1.25	7.5	11.27	8.75	15.15	-0870	8
1.25	6.25	10.02	7.5	13.9	-0770	7
—	5	8.77	6.25	12.65	-0670	6
—	3.75	7.52	5	11.4	-0570	5
—	2.5	6.27	3.75	10.15	-0470	4
—	—	5.02	2.5	8.9	-0370	3
—	—	3.77	1.25	7.65	53780-0270	2
E	D	C	B	A	EMBOSSED PACKAGE	CKT.
—					オーダー番号 ORDER No.	極数

CONNECTOR SERIES NO. 53780-**-**19

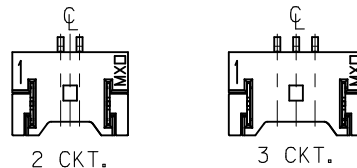
REVISED EC NO: J2010-1927 DRWN: KUROSE CHKD: KASAKAWA APPR: NUKITA 2010/03/25 2010/03/26 2010/03/29	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
		10 UNDER	± 0.2	DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT		
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE '04/04/15			
		30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/04/15			
		ANGULAR ±3 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-53780-003	SHEET NO. 1 OF 2	
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



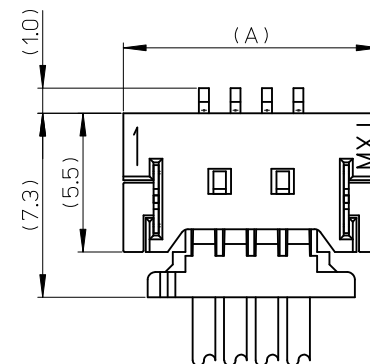
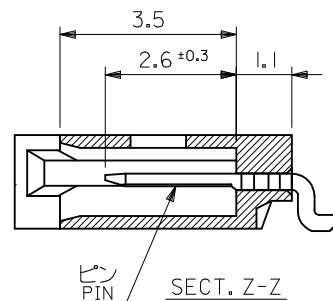
7~19極の奇数極に適用
APPLY FOR ODD CIRCUITS OF 7~19



8~30 極の偶数極に適用
APPLY FOR EVEN CIRCUITS OF 8~30



ロック形状図
LOCK CONFIGURATION



嵌合図 (SCALE 5:1)
MATED CONNECTORS (SCALE 5:1)

<div>REVISED</div> <div>EC NO.: J2010-1927</div> <div>DRWN:SKUROSE 2010/03/25</div> <div>CHKD:KASAKAWA 2010/03/26</div> <div>APPR:NUKITA 2010/03/29</div>		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		CONNECTOR SERIES NO. 53780-**19	
		10 UNDER	± 0.2	DRAWN BY	DATE	SCALE ---	DESIGN UNITS METRIC
		10 OVER 30 UNDER	± 0.25	T. UENO	'04/04/15	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT	
		30 OVER	± 0.3	CHECKED BY	DATE		
<div>REV</div> <div>DESCRIPTION</div>	<div>REV</div> <div>DESCRIPTION</div>	ANGULAR ± 3 °		APPROVED BY	DATE	MOLEX INCORPORATED	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		M. SASAO	'04/04/15		
		SIZE A3		SEE CHART		DOCUMENT NO. SD-53780-003	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO. 2 OF 2	

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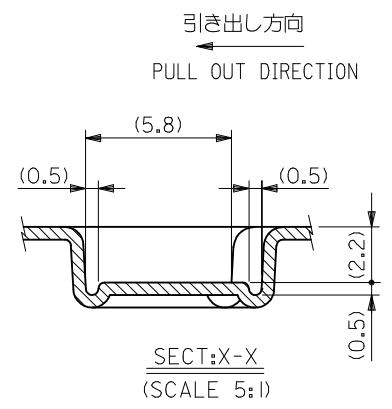
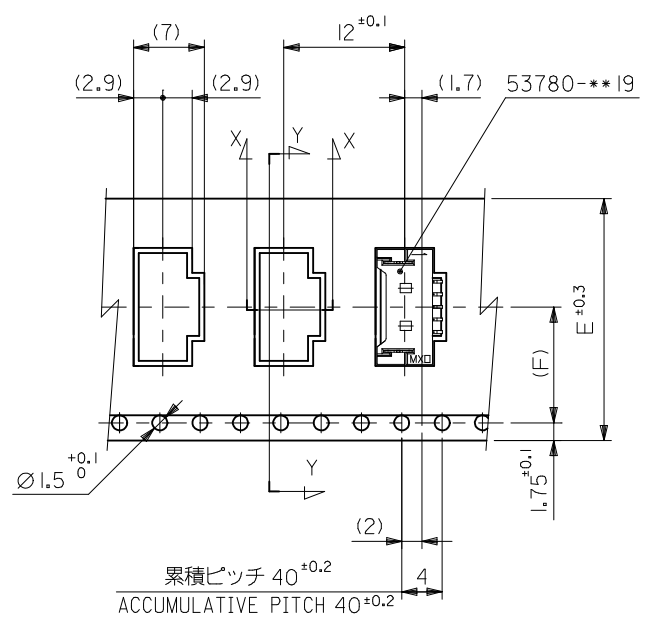
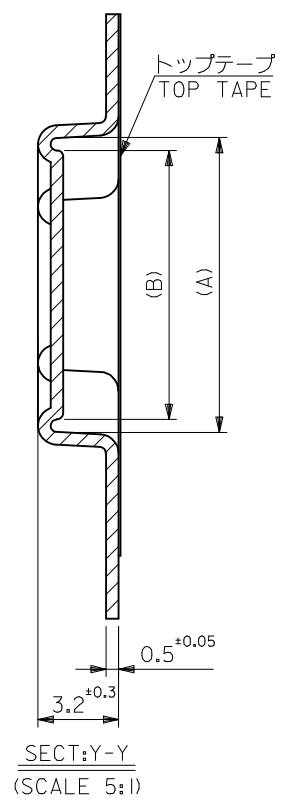
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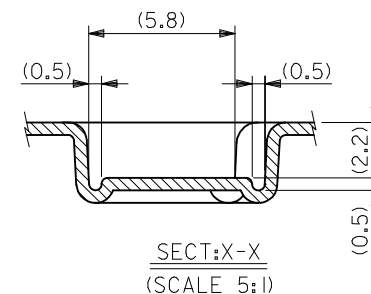
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


11.5	24	29.4	25.4	11.75	16.7	53780-0970	9
				10.5	15.45	53780-0870	8
				9.25	14.2	53780-0770	7
				8	12.95	53780-0670	6
				6.75	11.7	53780-0570	5
7.5	16	21.4	17.4	5.5	10.45	53780-0470	4
				4.25	9.2	53780-0370	3
(F)	E	D	C	3	7.95	53780-0270	2
キャリアテープ幅 CARRIER TAPE WIDTH				(B)	(A)	MATERIAL NO.	種数 CKT.
				MODEL NO.		53780-***70	

REVISED EC NO: J2010-0021 DRWN:MTAKASAKI CHKD:MIYASHI APPR:NUKITA REV B	DESCRIPTION 2009/07/07 2009/07/08 2009/07/08	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B WAFER ASSY EMBOSSD TAPE PACKAGE				
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/04/15					
		30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/04/15	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53780-004			2 OF 3	
				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



26.2	52.4	56	61.4	57.4	38	42.95	53780-3070	30
20.2	40.4	44	49.4	45.4	25.5	30.45	53780-2070	20
					25.5	27.95	53780-1870	18
					19.25	24.2	53780-1570	15
					18	22.95	53780-1470	14
					15.5	20.45	53780-1270	12
14.2	28.4	32	37.4	33.4	13	17.95	53780-1070	10
(G)	F	E キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極寸 CKT.

REVISED	EC NO. : J2010-0021	2009/07/07 DR.WATANAKAKASI	2009/07/08 CHKD.MIYASHI	2009/07/08 APPR.NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION
						10 UNDER	± 0.2	DRAWN BY T. UENO	DATE '04/04/15	TITLE 1.25 W/B WAFER ASSY EMBOSSED TAPE PACKAGE			
						10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE '04/04/15				
						30 OVER	± 0.3	APPROVED BY M. SASAO	DATE '04/04/15				
						ANGULAR ±3 °		MATERIAL NO.					
						REV	B	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SEE CHART	
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											